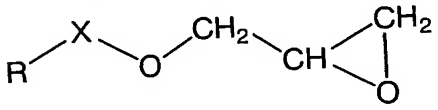
CLAIMS

1. An adhesive film obtainable by irradiating electron beam on a molded article obtainable by molding a resin composition comprising component (A) and component (B) below:

component (A): an epoxy group-containing copolymer obtainable by polymerizing monomer (a_1) and monomer (a_2) below:

monomer (a_1): ethylene and/or propylene

monomer (a_2): a monomer represented by formula (1) below:



(1)

(wherein R represents a aliphatic hydrocarbon group of a carbon number of from 2 to 18 having a double bond, at least one of hydrogen atoms of the aliphatic hydrocarbon group may be substituted with a halogen atom, a hydroxyl group or a carboxyl group, and X represents a single bond or a carbonyl group); and

component (B): a copolymer obtainable by polymerizing monomer (b_1) and monomer (b_2) below:

monomer (b_1): ethylene and/or propylene

monomer (b_2): α, β-unsaturated carboxylic acid anhydride.

2. The adhesive film according to claim 1, wherein the epoxy-containing copolymer of the component (A) is a melt-kneaded material.

3. The adhesive film according to claim 1 or 2, wherein the ratio by weight of component (A) to component (B) in the resin composition ((A)/(B)) is from 100/20 to 100/50.

4. The adhesive film according to claim 1, wherein component (B) is a copolymer obtainable by polymerizing monomer (b_1), monomer (b_2) and at least one selected from vinyl ester and an α, β-unsaturated carboxylic acid ester.

5. The adhesive film according to claim 1, wherein the ring-opening rate of the acid anhydride group derived from monomer (b_2) in component (B) is 1 to 50%, wherein the ring-opening rate of the acid anhydride is calculated by formula:

light absorbance [1] / light absorbance [2] × 100 (%), in which light absorbance [1] is a light absorbance measured at 1850 cm^{-1} of sample (1) with a thickness of 50 μm, obtained by heating component (B) at 150 °C for 2 minutes at normal pressure and then heating it again at 150 °C for 2 minutes under a pressurized pressure of 50 kg/cm^2, and light absorbance [2] is a light absorbance measured at 1850 cm^{-1} of sample (2) with a thickness of 50 μm, obtained by heating the component (B) at 230 °C for 2 minutes at normal pressure and then heating it again at 230 °C for 2 minutes under a pressurized pressure of 50 kg/cm^2.

6. The adhesive film according to claim 1, wherein the resin composition further contains an antioxidant (C).

7. The adhesive film according to claim 1, wherein the molded article is an article obtained by extrusion-molding.

8. The adhesive film according to claim 1, wherein the acceleration voltage of the electron beam is 50 to 300 kV.

9. The adhesive film according to claim 1, wherein the

irradiation dose of the electron beam is 10 to 300 kGy.

10. A storage method of the adhesive film according to claim 1, wherein the adhesive film is preserved at a temperature of -10°C or lower.

11. A laminate obtainable by laminating the adhesive film according to claim 1 on an adherent and thermally curing the adhesive film.